

**METHOD OF HEATING A SUBSTRATE IN A VARIABLE TEMPERATURE
PROCESS USING A FIXED TEMPERATURE CHUCK**

Abstract of the Disclosure

A method is provided for heating a substrate in a process chamber using a heated chuck. In accordance with the method, the substrate is lowered onto the chuck and heated to a first temperature less than a temperature of the chuck. The substrate is then raised away from the chuck, and a process is carried out on the substrate while the substrate is supported above the chuck. The substrate is then lowered back to the chuck and heated to a second temperature greater than the first temperature for further processing of the substrate.

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